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TECHNICAL REPORT

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Thermal standardization on semiconductor packages – Part 1: Thermal resistance and thermal parameter of BGA, QFP type semiconductor packages

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CONTENTS

FOREWORD 3
1 Scope 5
2 Normative references 5
3 Terms and definitions 5
3.1 Terms and letter symbols related to temperature (unit [°C or K]) 5
3.2 Terms and letter symbols related to thermal characteristics 6
4 Accuracy of θ_{JA} 10
4.1 Variation of θ_{JA} 10
4.1.1 General 10
4.1.2 Analysis model 10
4.1.3 Simulation conditions (typical values) 11
4.1.4 Evaluation items and standards 11
4.1.5 Evaluation results 12
4.1.6 Summary 17
4.2 Discrepancy of θ_{JA} 18
5 Guideline for thermal design 19
Bibliography 20

Figure 1 – Definition of temperature 6
Figure 2 – Definition of thermal resistance 7
Figure 3 – Thermal resistance 8
Figure 4 – Thermal resistance and thermal characterization parameter 9
Figure 5 – Thermal characterization parameter 10
Figure 6 – Simulation conditions 11
Figure 7 – θ_{JA} dependence on board remaining copper rate (BGA) 12
Figure 8 – θ_{JA} dependence on remaining copper rate (LQFP) 13
Figure 9 – θ_{JA} dependence on ambient air temperature T_A (BGA) 14
Figure 10 – θ_{JA} dependence on ambient air temperature T_A (LQFP) 15
Figure 11 – θ_{JA} dependence on power dissipation (BGA) 16
Figure 12 – θ_{JA} dependence on power dissipation (LQFP) 17
Figure 13 – Influence items and their impact on θ_{JA} 17
Figure 14 – The gap of θ_{JA} by the difference of the environment 19

Table 1 – Evaluation items and evaluation parameters 11

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Full document details: IEC TR 63378-1-2021

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THERMAL STANDARDIZATION ON SEMICONDUCTOR PACKAGES –

Part 1: Thermal resistance and thermal parameter of BGA, QFP type semiconductor packages

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IEC TR 63378-1 has been prepared by subcommittee 47D: Semiconductor devices packaging, of IEC technical committee 47: Semiconductor devices. It is a Technical Report.

The text of this Technical Report is based on the following documents:

Draft	Report on voting
47D/928/DTR	47D/935/RVDTR

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this Technical Report is English.

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A list of all parts in the IEC 63378 series, published under the general title *Thermal standardization on semiconductor packages*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

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- withdrawn,
- replaced by a revised edition, or
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THERMAL STANDARDIZATION ON SEMICONDUCTOR PACKAGES –

Part 1: Thermal resistance and thermal parameter of BGA, QFP type semiconductor packages

1 Scope

This part of IEC 63378 specifies the terms and definitions that are commonly used for thermal characteristics of BGA and QFP type semiconductor packages, and guidelines to use these thermal characteristics.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191-4, *Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor device packages*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60191-4 and the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

3.1 Terms and letter symbols related to temperature (unit [°C or K])

3.1.1
ambient air temperature
T_A
temperature of ambient air at location adequately distant from the package (see Figure 1)

Note 1 to entry: Conceptually, it refers to an ambient air temperature at a location that is not affected by the semiconductor package to be measured.

3.1.2
junction temperature
T_J
temperature of at an arbitrary position of the chip (see Figure 1)

Note 1 to entry: Especially when there is no specification, it is considered as the centre of a chip.

Note 2 to entry: Junction refers to the junction area of a semiconductor. Assuming that heat is generated at the junction of p-type and n-type, temperature at the junction becomes high and is used as representing temperature for semiconductor devices. Because there are many junctions built into a real chip, the term junction is used synonymously as the chip. The location is commonly placed at the centre of the circuit surface of the chip, although location dependence may be taken into consideration for chips requiring high power consumption.

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3.1.3
case temperature
T_C
temperature at an arbitrary position on the surface of a package (see Figure 1)

Note 1 to entry: Especially when there is no specification, it is considered as the centre of a chip upper part.

3.1.4
top temperature
T_T
temperature at the centre of the package's upper surface (see Figure 1)

Note 1 to entry: Defined as T_T due to T_C used as definition for special surface at back of package of power device, etc. For normal package such as BGA, T_C and T_T are used synonymously.

3.1.5
board temperature
T_B
temperature of the board which is distant from an arbitrary end of a package 1 mm (see Figure 1)

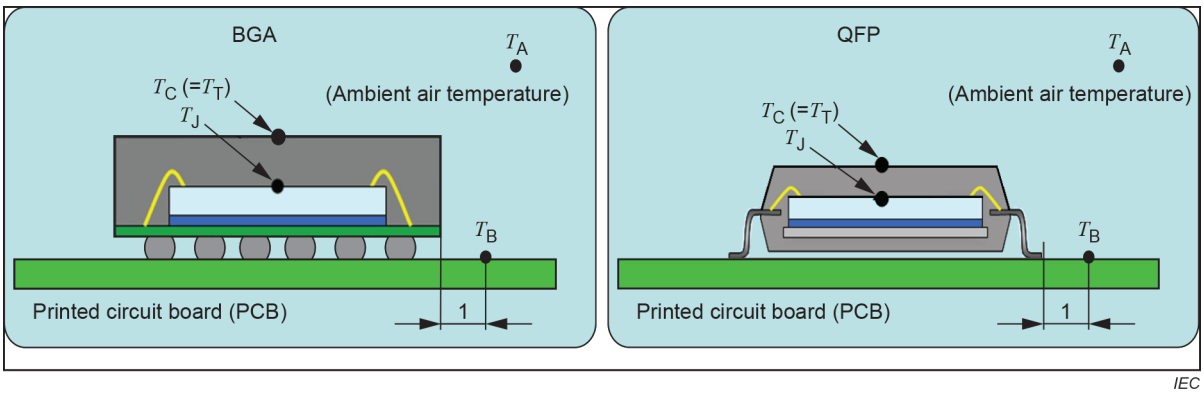

Figure 1 – Definition of temperature

3.2 Terms and letter symbols related to thermal characteristics

3.2.1
thermal resistance
quotient of the difference between the virtual temperature of the device and the temperature of a stated external reference point, by the steady-state power dissipation in the device (see Figure 2)

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